



SEMIPACK® 3

Rectifier Diode Modules

SKKD 353/18

Features*

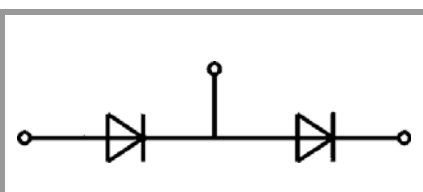
- Industrial standard package
- Electrically insulated base plate
- Heat transfer through aluminum oxide ceramic insulated metal base plate
- Chip soldered on direct copper bonded Al_2O_3 ceramic
- UL recognition, file no. E63532

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Recitifier Diode				
I _{FAV}	sin. 180°	T _c = 85 °C	350	A
	T _{j max} = 130 °C	T _c = 100 °C	260	A
I _{FRMS}	continuous operation		580	A
I _{FSM}	10 ms	T _j = 25 °C	10500	A
		T _j = 130 °C	9500	A
i ² t	10 ms	T _j = 25 °C	551250	A ² s
		T _j = 130 °C	451250	A ² s
V _{RSM}	T _j = 25 °C		1900	V
V _{RRM}	T _j = 25 °C		1800	V
T _j			-40 ... 130	°C
Module				
T _{stg}			-40 ... 125	°C
V _{isol}	a.c.; 50 Hz; r.m.s.	1 min	3000	V
		1 s	3600	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Diode					
V_F	$T_j = 25^\circ\text{C}$, $I_F = 750\text{ A}$			1.38	V
V_{F0}	$T_j = 130^\circ\text{C}$			0.84	V
r_F	$T_j = 130^\circ\text{C}$			0.67	$\text{m}\Omega$
I_R	$T_j = 130^\circ\text{C}$, $V_{\text{RD}} = V_{\text{RRM}}$			15	mA
$R_{\text{th(j-c)}}$	cont.			0.09	K/W
				per chip	
				per module	
$R_{\text{th(j-c)}}$	sin. 180°			0.092	K/W
				per chip	
				per module	
Module					
$R_{\text{th(c-s)}}$	chip		0.08		K/W
	module		0.04		K/W
M_s	to heatsink M5	4.25		5.75	Nm
M_t	to terminals M8	7.65		10.35	Nm
a				5 * 9.81	m/s^2
w			410		g



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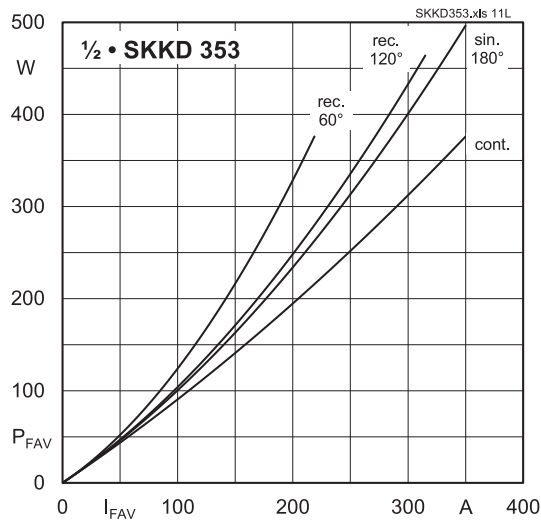


Fig. 11L: Power dissipation per diode vs. forward current

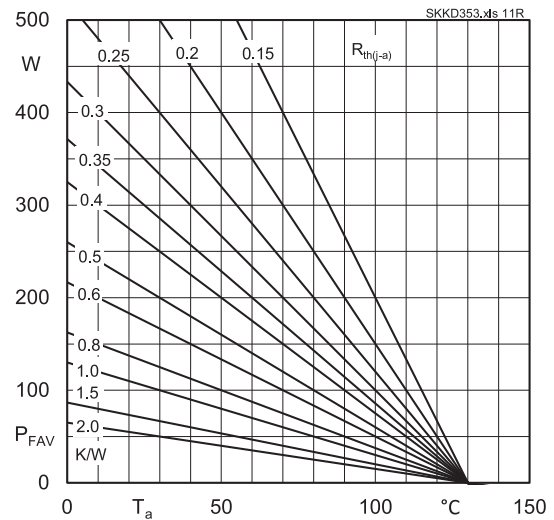


Fig. 11R: Power dissipation per diode vs. ambient temperature

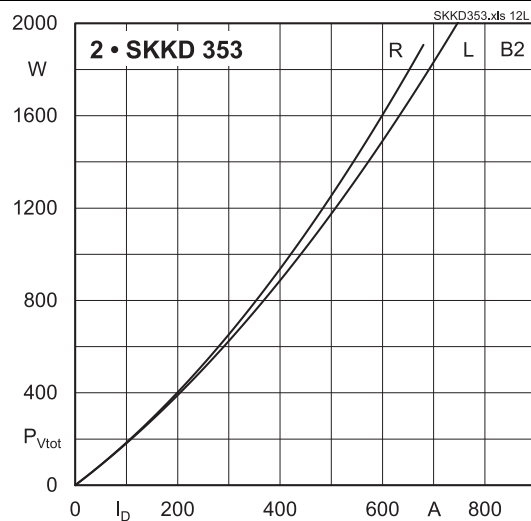


Fig. 12L: Power dissipation of two modules vs. direct current

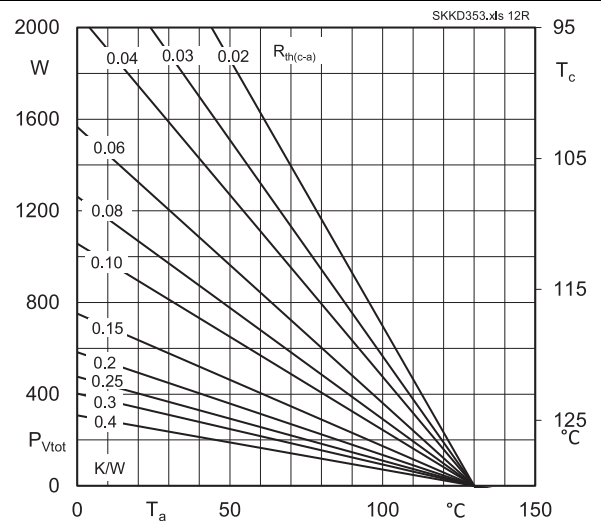


Fig. 12R: Power dissipation of two modules vs. case temperature

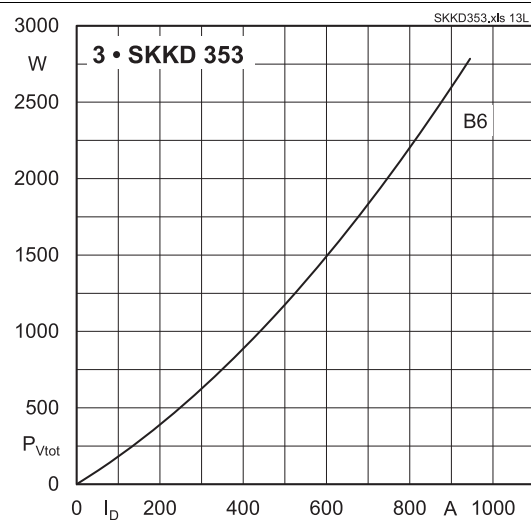


Fig. 13L: Power dissipation of three modules vs. direct current

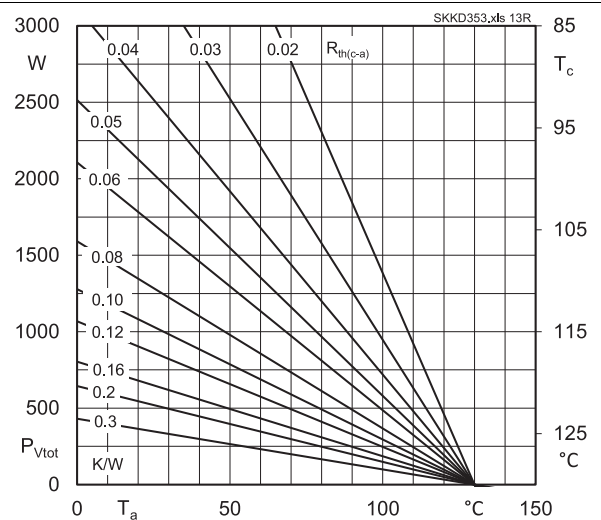


Fig. 13R: Power dissipation of three modules vs. case temperature

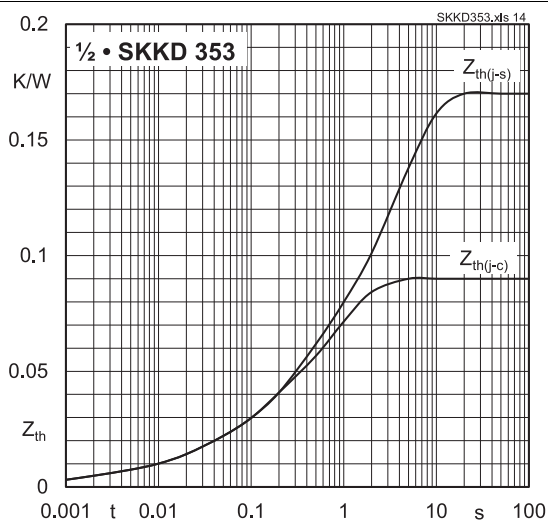


Fig. 14: Transient thermal impedance vs. time

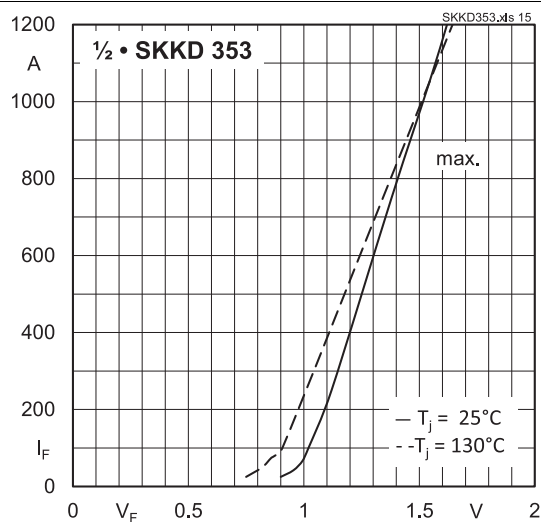


Fig. 15: Forward characteristics

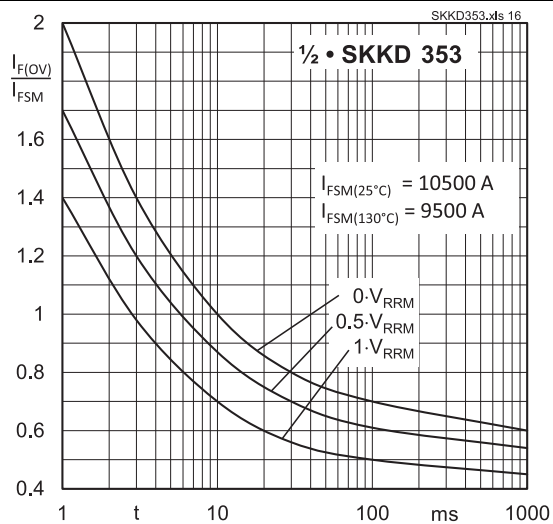
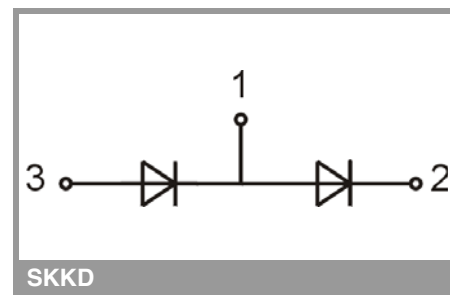
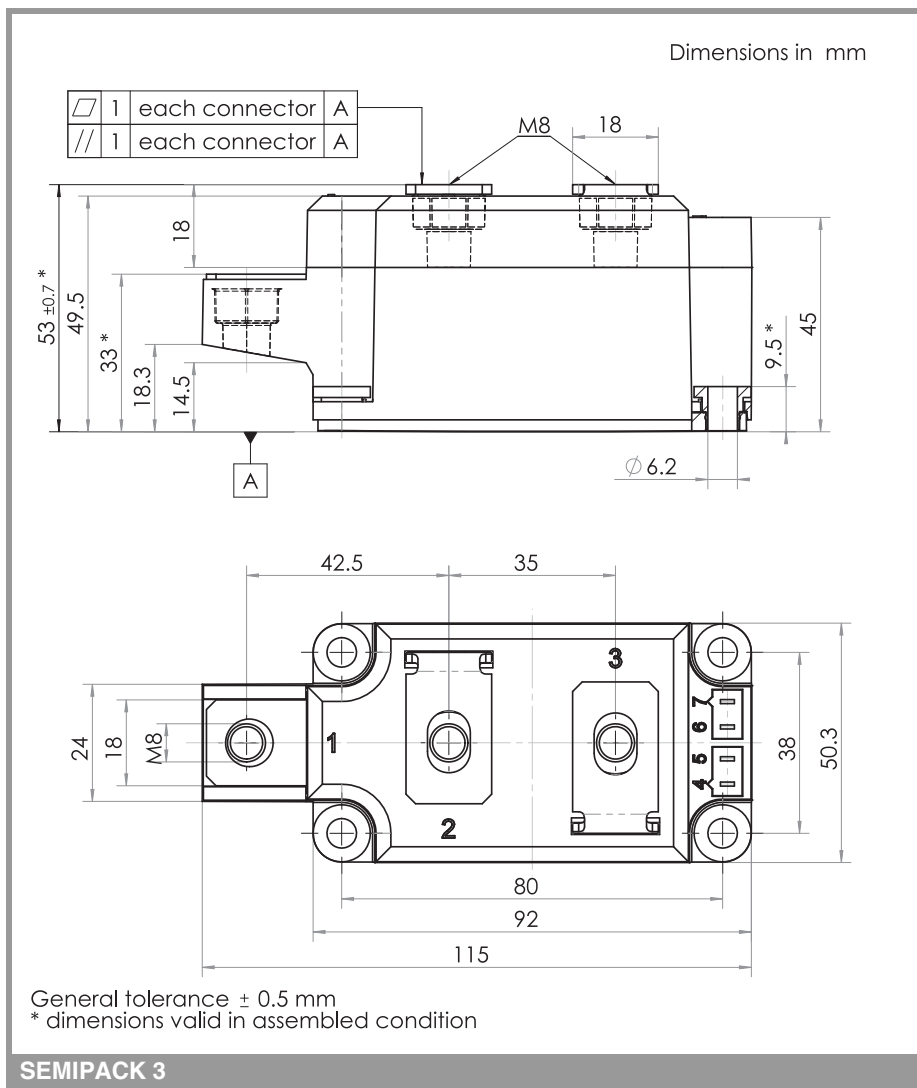


Fig. 16: Surge overload current vs. time



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

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